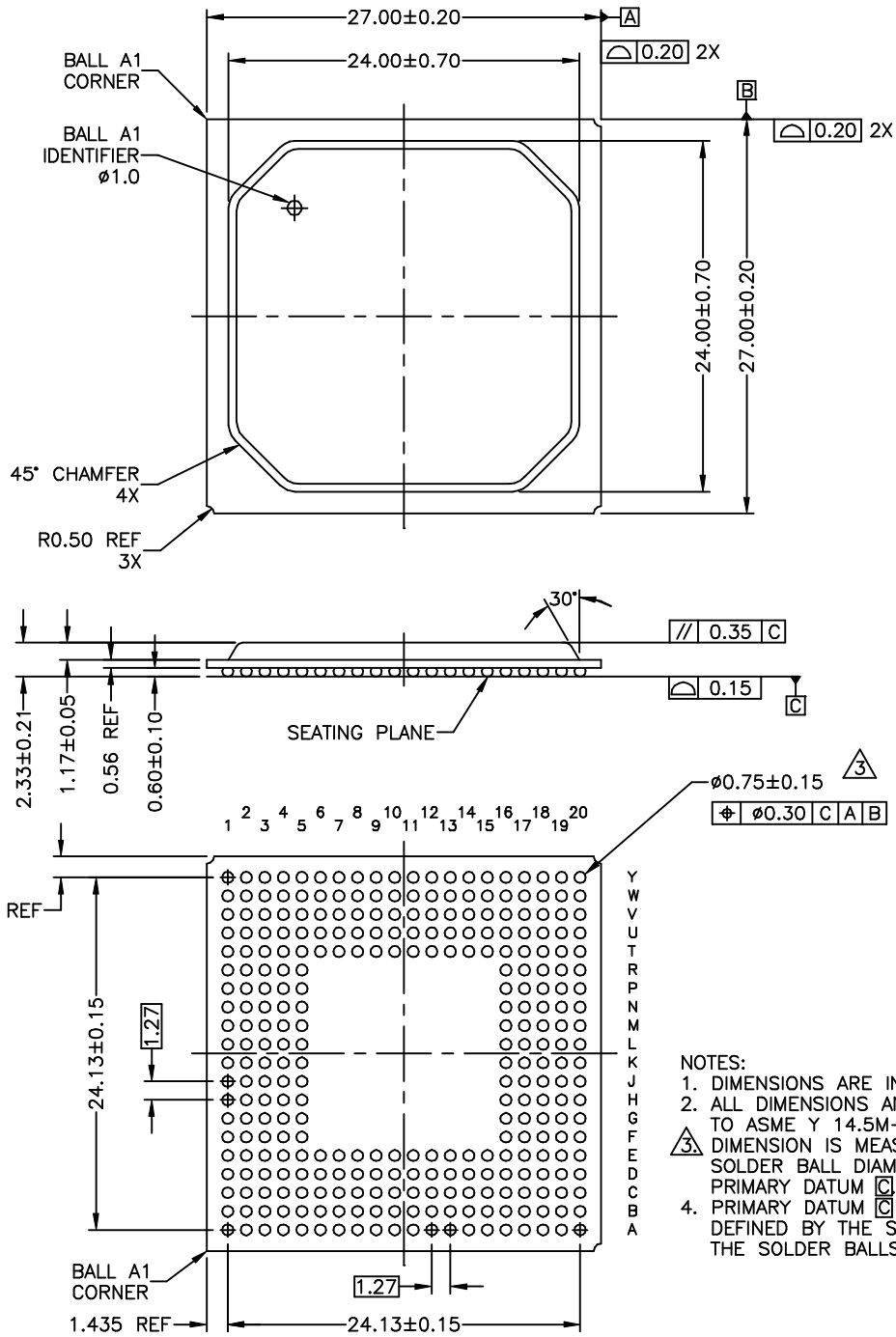




SIGNATURE		DATE		 Dallas Semiconductor	
DOC. CONTROL:					
ENGR. MGR:				TITLE MARKETING OUTLINE – 300L PBGA(27x27) 1.27 PITCH, 2.33 THICK, 4 LAYER	
MFG. ENGR:					
CHECKED BY:					
DRAWN BY:		SIZE A	FSCM NO	PART NO.	REV A
DO NOT SCALE DWG.			SCALE 2/1	SHEET 1 OF 1	